

### **Description**

The HSS233 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

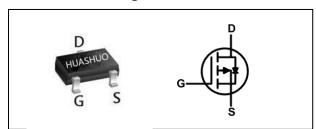
The HSS2333 meet the RoHS and Green Product requirement with full function reliability approved.

#### **Product Summary**

| V <sub>D</sub> S | -12  | V  |
|------------------|------|----|
| RDS(ON),typ      | 15.3 | mΩ |
| lo               | -8   | Α  |

- Super Low Gate Charge
- Green Device Available
- Excellent CdV/dt effect decline
- Advanced high cell density Trench technology

#### **SOT 23 Pin Configurations**



#### **Absolute Maximum Ratings**

| Symbol     | Parameter                              | Rating     | Units |
|------------|--|------------|-------|
| Vos        | Drain-Source Voltage -12               |            | V     |
| Vgs        | Gate-Source Voltage                    | ±12        | V     |
| Id@Ta=25°C | Continuous Drain Current, Vgs @ -4.5V1 | -8         | А     |
| Id@Ta=70°C | Continuous Drain Current, Ves @ -4.5V1 | -6.8       | А     |
| Ідм        | Pulsed Drain Current <sub>2</sub>      | -32        | А     |
| PD@TA=25°C | Total Power Dissipation3               | 1.2        | W     |
| Тѕтс       | Storage Temperature Range              | -55 to 150 | °C    |
| TJ         | Operating Junction Temperature Range   | -55 to 150 | °C    |

## **Thermal Data**

| Symbol | Parameter                             | Тур. | Max. | Unit |
|--------|---------------------------------------|------|------|------|
| Reja   | Thermal Resistance Junction-Ambient 1 |      | 100  | °C/W |



## Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

| Symbol              | Parameter                                   | Conditions   | Min. | Тур.   | Max. | Unit  |
|---------------------|---|--|------|--------|------|-------|
| BVpss               | Drain-Source Breakdown Voltage              | Vgs=0V , Ip=-250uA   | -12  |        |      | V     |
| △BVɒss/△Tɹ          | BV <sub>DSS</sub> Temperature Coefficient   | Reference to 25°C , ID=-1mA  |      | -0.014 |      | V/°C  |
| Descent             | Static Drain-Source On-Resistance2          | Vgs=-4.5V , ID=-8A   |      | 15.3   | 18   | mΩ    |
| Rds(on)             |   | Vgs=-2.5V , ID=-6A   |      | 20.8   | 28   |       |
| VGS(th)             | Gate Threshold Voltage                      | Voc Voc In 2500A   | -0.4 | -0.68  | -1.2 | V     |
| △VGS(th)            | V <sub>GS(th)</sub> Temperature Coefficient | Vgs=Vps , In =-250uA   |      | 3.95   |      | mV/°C |
| lace                | Drain Source Leakage Current                | V <sub>DS</sub> =-12V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C<br>V <sub>DS</sub> =-12V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C |      |        | -1   |       |
| IDSS                | Drain-Source Leakage Current                |  |      |        | -5   | uA    |
| Igss                | Gate-Source Leakage Current                 | Vgs=±12V, Vps=0V   |      |        | ±100 | nA    |
| gfs                 | Forward Transconductance                    | Vps=-5V , Ip=-8A   |      | 5      |      | S     |
| Qg                  | Total Gate Charge (-4.5V)                   |  |      | 35     |      |       |
| Qgs                 | Gate-Source Charge                          | V <sub>DS</sub> =-6V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-5A  |      | 5      |      | nC    |
| Qgd                 | Gate-Drain Charge                           |  |      | 10     |      |       |
| T <sub>d</sub> (on) | Turn-On Delay Time                          |  |      | 11     |      |       |
| Tr                  | Rise Time                                   | V <sub>DD=-6</sub> V , V <sub>GS=-4.5</sub> V , R <sub>G</sub> =3.3Ω, I <sub>D=-5</sub> A  |      | 33     |      |       |
| T <sub>d(off)</sub> | Turn-Off Delay Time                         |  |      | 31     |      | ns    |
| Tf                  | Fall Time                                   |  |      | 10     |      |       |
| Ciss                | Input Capacitance                           | VDS=-6V , VGS=0V , f=1MHz  |      | 2700   |      |       |
| Coss                | Output Capacitance                          |  |      | 680    |      | pF    |
| Crss                | Reverse Transfer Capacitance                |  |      | 589    |      |       |

## **Diode Characteristics**

| Symbol | Parameter                                | Conditions   | Min. | Тур. | Max. | Unit |
|--------|--|--|------|------|------|------|
| Is     | Continuous Source Current <sub>1,4</sub> | V <sub>G</sub> =V <sub>D</sub> =0V , Force Current | -    |      | -8   | Α    |
| Isм    | Pulsed Source Current <sub>2,4</sub>     |  | -    |      | -32  | Α    |
| Vsp    | Diode Forward Voltage2                   | Vgs=0V , Is=-1A , TJ=25°C                          |      |      | -1.2 | V    |

#### Note:

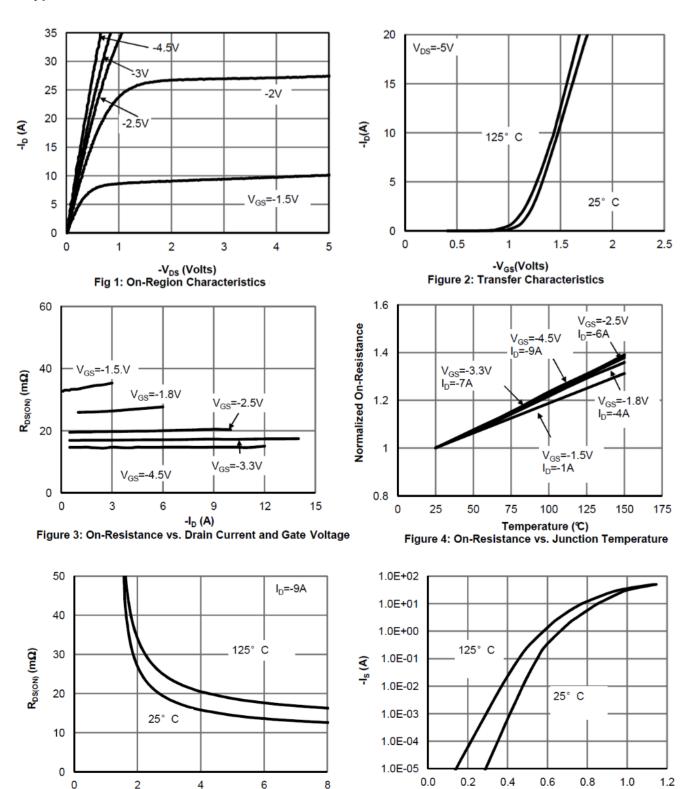
<sup>1.</sup> The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.

<sup>2.</sup>The data tested by pulsed , pulse width  $\le 300 us$  , duty cycle  $\le 2\%$  3.The power dissipation is limited by 150  $^{\circ}C$  junction temperature

<sup>4.</sup>The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.



#### **Typical Characteristics**



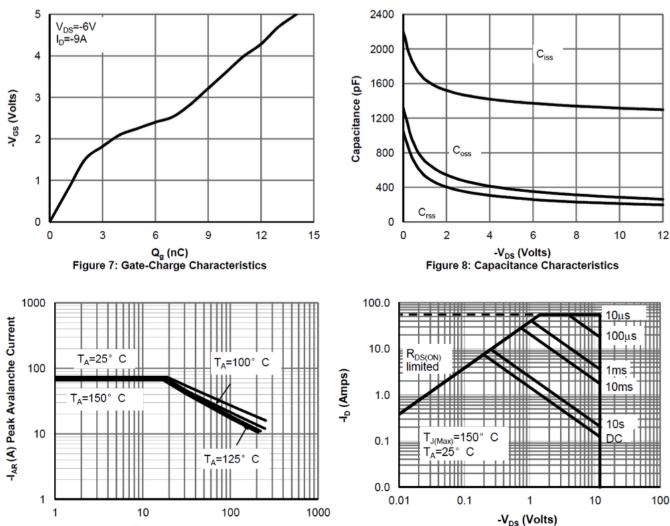
-V<sub>SD</sub> (Volts)

Figure 6: Body-Diode Characteristics

-V<sub>GS</sub> (Volts)

Figure 5: On-Resistance vs. Gate-Source Voltage





Time in avalanche,  $t_{\text{A}}$  ( $\mu$ s) Figure 9: Single Pulse Avalanche capability

Figure 10: Maximum Forward Biased Safe Operating Area

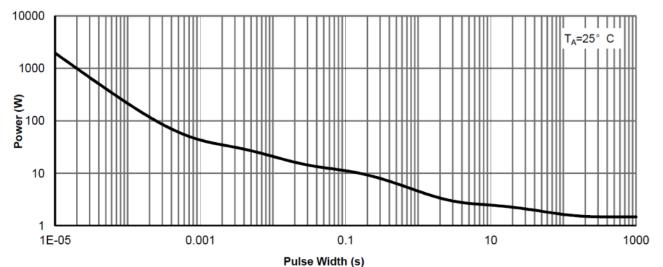


Figure 11: Single Pulse Power Rating Junction-to-Ambient



# **Ordering Information**

| Part Number | Package code | Packaging      |
|-------------|--------------|----------------|
| HSS2333     | SOT-23L      | 3000/Tape&Reel |

